L Number	Hits	Search Text	DB	Time stamp
-	188963	interconnection	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/02 07:28
-	52554	conductive same polymer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/01 15:37
-	6307	(solder or solderable) same (preform or cap)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/01 15:27
-	281564	(electric or electrical) near7 connection	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/01 15:27
-	124	interconnection and (conductive same polymer) and ((solder or solderable) same (preform or cap)) and ((electric or electrical) near7 connection)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/01 15:28
-	22689	conductive near2 adhesive	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/01 15:37
-	693	interconnection same (conductive near2 adhesive)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/01 15:37
-	180508	solder or solderable	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/01 15:37
-	450	(interconnection same (conductive near2 adhesive)) and (solder or solderable)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/01 15:37
-	16773	(solder or solderable) near2 ball	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/01 15:38
-	139	((interconnection same (conductive near2 adhesive)) and (solder or solderable)) and ((solder or solderable) near2 ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/01 15:38
-	969	resin near ball	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/02 07:28
-	87	(resin near ball) and solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/02 07:34

C:\APPS\east\workspaces\09911069.wsp

-	700	solder near2 cap	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/02 07:38
-	151	(solder near2 cap) and adhesive	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/02 07:34
-	16808	solder near2 ball	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/02 07:38
-	2212	(solder near2 ball) same adhesive	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/02 07:39
-	28	((solder near2 ball) same adhesive) same preform	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/02 07:40
-	161	((solder near2 ball) same adhesive) same interconnection	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/02 07:45
-	11	(ball near2 solder near2 adhesive) same (preform or interconnection)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/02 08:14
-	45828	conductive near (polymer or resin or adhesive)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/02 08:14
-	18833	flip near chip	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/02 08:18
-	2219	(flip near chip) same interconnection	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/02 08:18
-	4687	(conductive near (polymer or resin or adhesive)) same solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/02 08:18
-	350	((flip near chip) same interconnection) and ((conductive near (polymer or resin or adhesive)) same solder)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/02 08:23
-	2	("5925930").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/02 08:23

–	28	("3320658" | "3396894" | "3472365" | "3516155" | "3719981" | "3744129" | "3795884" | "3926360" | "3982320" | "3991463" | "3998512" | "4027936" | "4064623" | "4067104" | "4089575" | "4144648" | "4195193" | "4209893" | "4216350" | "4295700" | "4334727" | "4354629" | "4390220" | "4402450" | "4412642" | "4445736" | "4458968" | "4556276").PN.	USPAT	2003/10/02 09:31
–	24	4712721.URPN.	USPAT	2003/10/02 09:32
–	12	("5136365" | "5187020" | "5375042" | "5412539" | "5509200" | "5518674" | "5805426" | "5893765" | "5905638" | "5910641" | "6090633" | "6326561").PN.	USPAT	2003/10/02 09:34
–	0	6600224.URPN.	USPAT	2003/10/02 09:35
–	1	"3002481".PN.	USPAT	2003/10/02 09:36
–	20	3744129.URPN.	USPAT	2003/10/02 09:37
–	14	("3472365" | "4209893" | "4216350" | "4437232" | "4712721" | "4842184" | "4903889" | "5029748" | "5323947" | "5363277" | "5373984" | "5388327" | "5438223" | "5497938").PN.	USPAT	2003/10/02 09:37

C:\APPS\east\workspaces\09911069.wsp